

Electronic Patent Application Fee Transmittal

Application Number:	10571142			
Filing Date:	22-Nov-2006			
Title of Invention:	Semiconductor substrate cutting method			
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Filer:	Joseph John Buczynski/Towanna Bolling			
Attorney Docket Number:	46884-5461			
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Basic Filing:				
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Miscellaneous-Filing:				
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Patent-Appeals-and-Interference:				
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Extension - 3 months with \$0 paid	1253	1	1110	1110

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